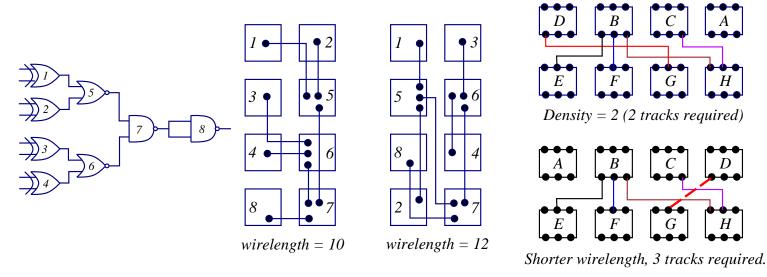
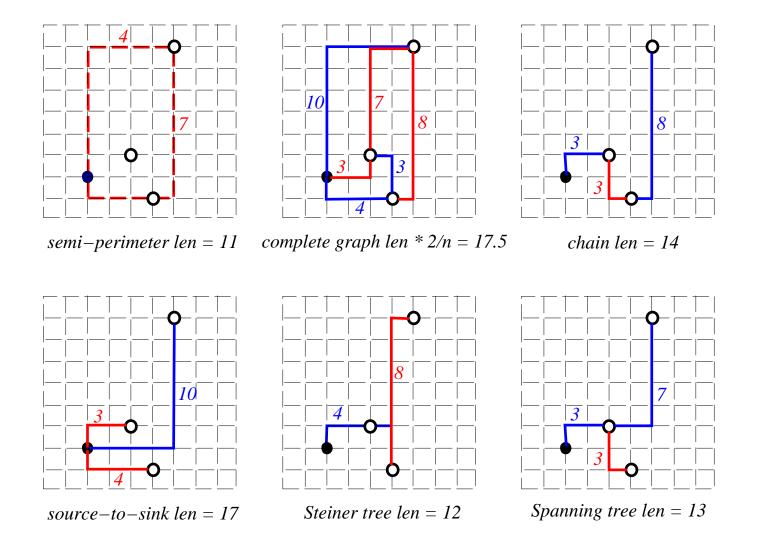
#### **Placement**

- The process of arranging the circuit components on a layout surface.
- Inputs: A set of fixed modules, a netlist.
- Goal: Find the best position for each module on the chip according to appropriate cost functions.
  - Considerations: routability/channel density, wirelength, cut size, performance, thermal issues, I/O pads.



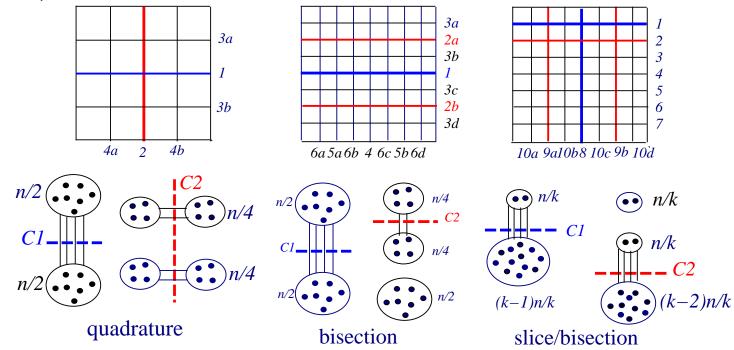
## **Estimation of Wirelength**

- **Semi-perimeter method:** Half the perimeter of the bounding rectangle that encloses all the pins of the net to be connected. Most widely used approximation!
- Complete graph: Since #edges in a complete graph  $(\frac{n(n-1)}{2})$  is  $\frac{n}{2} \times \#$  of tree edges (n-1),  $wirelength \approx \frac{2}{n} \sum_{(i,j) \in net} dist(i,j)$ .
- Minimum chain: Start from one vertex and connect to the closest one, and then to the next closest, etc.
- Source-to-sink connection: Connect one pin to all other pins of the net. Not accurate for uncongested chips.
- Steiner-tree approximation: Computationally expensive.
- Minimum spanning tree



#### Min-Cut Placement

- Breuer, "A class of min-cut placement algorithms," DAC-77.
- Quadrature: suitable for circuits with high density in the center.
- Bisection: good for standard-cell placement.
- Slice/Bisection: good for cells with high interconnection on the periphery.



### Algorithm for Min-Cut Placement

```
Algorithm: Min_Cut_Placement(N, n, C)

/* N: the layout surface */

/* n: # of cells to be placed */

/* n_0: # of cells in a slot */

/* C: the connectivity matrix */

1 begin

2 if (n \le n_0) then PlaceCells(N, n, C);

3 else

4 (N_1, N_2) \leftarrow \text{CutSurface}(N);

5 (n_1, C_1), (n_2, C_2) \leftarrow \text{Partition}(n, C);

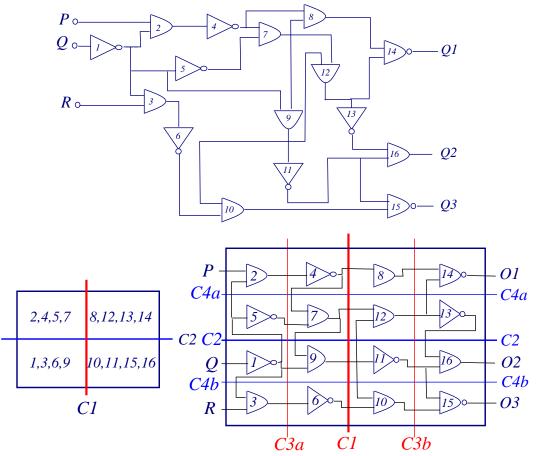
6 Call Min_Cut_Placement(N_1, n_1, C_1);

7 Call Min_Cut_Placement(N_2, n_2, C_2);

8 end
```

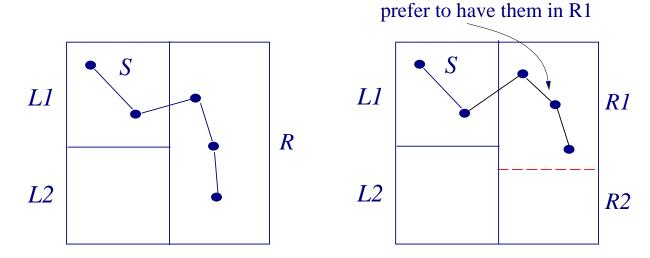
# **Quadrature Placement Example**

• Apply K-L heuristic to partition + Quadrature Placement: Cost  $C_1=4$ ,  $C_{2L}=C_{2R}=2$ , etc.



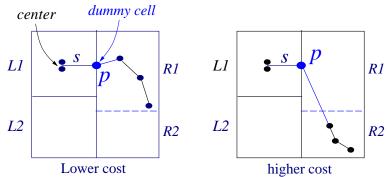
## Min-Cut Placement with Terminal Propagation

- Dunlop & Kernighan, "A procedure for placement of standard-cell VLSI circuits," IEEE TCAD, Jan. 1985.
- Drawback of the original min-cut placement: Does not consider the positions of terminal pins that enter a region.
  - What happens if we swap {1, 3, 6, 9} and {2, 4, 5, 7} in the previous example?



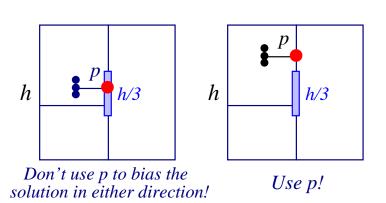
# **Terminal Propagation**

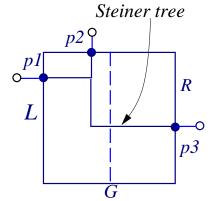
• We should use the fact that s is in  $L_1$ !



P will stay in R1 for the rest of partitioning!

ullet When not to use p to bias partitioning? Net s has cells in many groups?

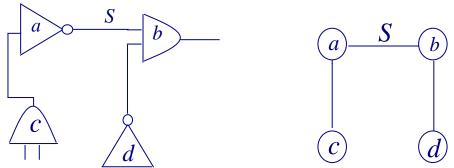


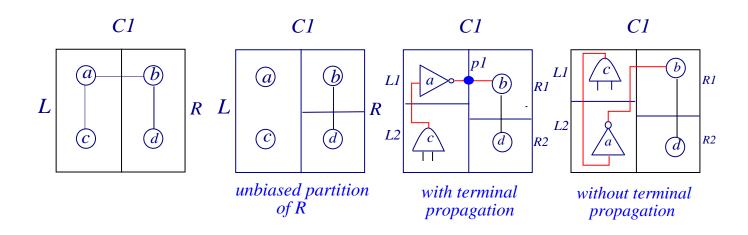


minimum rectilinear

# **Terminal Propagation Example**

• Partitioning must be done breadth-first, not depth-first.



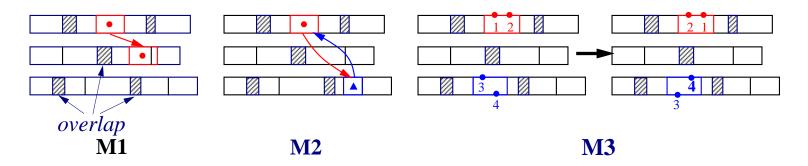


## Placement by Simulated Annealing

- Sechen and Sangiovanni-Vincentelli, "The TimberWolf placement and routing package," IEEE J. Solid-State Circuits, Feb. 1985; "TimberWolf 3.2: A new standard cell placement and global routing package," DAC-86.
- TimberWolf: Stage 1
  - Modules are moved between different rows as well as within the same row.
  - Modules overlaps are allowed.
  - When the temperature is reached below a certain value, stage 2 begins.
- TimberWolf: Stage 2
  - Remove overlaps.
  - Annealing process continues, but only interchanges adjacent modules within the same row.

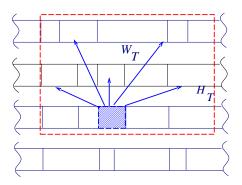
## Solution Space & Neighborhood Structure

- **Solution Space:** All possible arrangements of the modules into rows, possibly with overlaps.
- Neighborhood Structure: 3 types of moves
  - $M_1$ : Displace a module to a new location.
  - $-M_2$ : Interchange two modules.
  - $-M_3$ : Change the orientation of a module.



### **Neighborhood Structure**

- TimberWolf first tries to select a move between  $M_1$  and  $M_2$ :  $Prob(M_1) = 0.8$ ,  $Prob(M_2) = 0.2$ .
- If a move of type  $M_1$  is chosen and it is rejected, then a move of type  $M_3$  for the same module will be chosen with probability 0.1.
- Restrictions: (1) what row for a module can be displaced? (2) what pairs of modules can be interchanged?
- Key: Range Limiter
  - At the beginning,  $(W_T, H_T)$  is very large, big enough to contain the whole chip.
  - Window size shrinks slowly as the temperature decreases. Height and width  $\propto log(T)$ .
  - Stage 2 begins when window size is so small that no inter-row module interchanges are possible.



#### **Cost Function**

- Cost function:  $C = C_1 + C_2 + C_3$ .
- $C_1$ : total estimated wirelength.
  - $C_1 = \sum_{i \in Nets} (\alpha_i w_i + \beta_i h_i)$
  - $\alpha_i, \beta_i$  are horizontal and vertical weights, respectively. ( $\alpha_i = 1, \beta_i = 1 \Rightarrow \frac{1}{2} \times$  perimeter of the bounding box of Net i.)
  - Critical nets: Increase both  $\alpha_i$  and  $\beta_i$ .
  - If vertical wirings are "cheaper" than horizontal wirings, use smaller vertical weights:  $\beta_i < \alpha_i$ .
- $C_2$ : penalty function for module overlaps.
  - $C_2 = \gamma \sum_{i \neq j} O_{ij}^2$ ,  $\gamma$ : penalty weight.
  - $O_{ij}$ : amount of overlaps in the x-dimension between modules i and j.
- $C_3$ : penalty function that controls the row length.
  - $C_2 = \delta \sum_{r \in Rows} |L_r D_r|$ ,  $\delta$ : penalty weight.
  - $D_r$ : desired row length.
  - $L_r$ : sum of the widths of the modules in row r.

### **Annealing Schedule**

- $T_k = r_k T_{k-1}, k = 1, 2, 3, \dots$
- $\bullet$   $r_k$  increases from 0.8 to max value 0.94 and then decreases to 0.8.
- ullet At each temperature, a total # of nP attempts is made. n: # of modules; P: user specified constant.
- Termination: T < 0.1.